

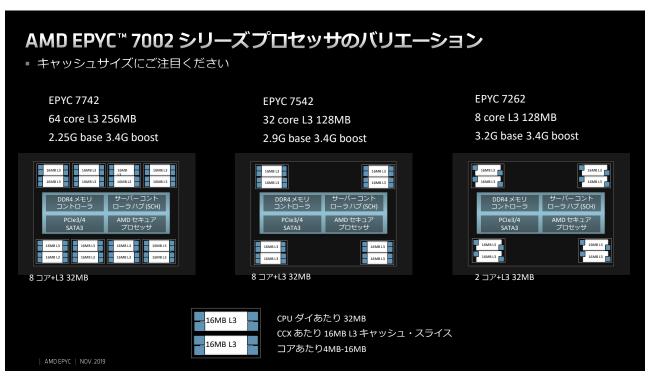


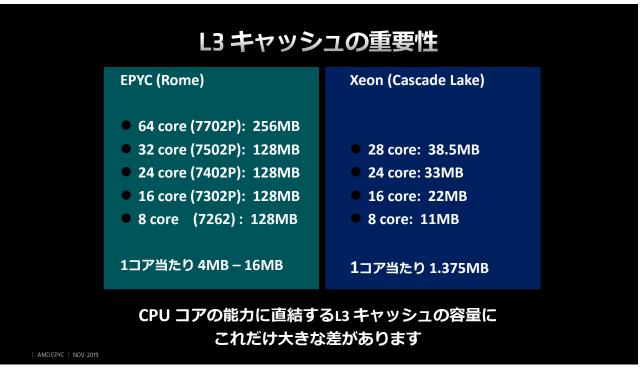
ロードマップ製品一覧

モデル番号	コア敷	スレッド数	ベース周波敷 (GHz)	最大プースト 周波数(GHz) ^a	TDP (W)	L3 キャッシュ (MB)	DDR チャネル教	最大DDR 周波数 (1DPC)	ソケット当たり理論 メモリバンド幅 (GB/s)	PCle Gen 4 レーン数
7742	64	128	2.25	3.4	225	256	8	3200	204.8	128
7702 7202P	64	128	2.0	3.35	200	256	8	3200	204.8	128
7642	48	96	2.3	3.3	225	256	8	3200	204.8	128
7552	48	96	2.2	3.3	200	192	8	3200	204.8	128
7542	32	64	2.9	3.4	225	128	8	3200	204.8	128
7502 7502P	32	64	2.5	3.35	180	128	8	3200	204.8	128
7452	32	64	2.35	3.35	155	128	8	3200	204.8	128
7402 7402P	24	48	2.8	3.35	180	128	8	3200	204.8	128
7352	24	48	2.3	3.2	155	128	8	3200	204.8	128
7302 7302P	16	32	3.0	3.3	155	128	8	3200	204.8	128
7282	16	32	2.8	3.2	120	64	8	3200	85.3 ^b	128
7272	12	24	2.9	3.2	120	64	8	3200	85.3 ^b	128
7262	8	16	3.2	3.4	155	128	8	3200	204.8	128
7252	8	16	3.1	3.2	120	64	8	3200	85.3 ^b	128
7252P	8	16	3.1	3.2	120	32	8	3200	85.3 ^b	128

a. プロセッサが動作可能な最大シングルコア周波数 b. DDR4-2667 DIMM 4チャネルでの動作に最適化

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スループットの飛躍的な向上

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- 業界初の PCIe® Gen 4 対応 CPU
- PCle Gen 3に対して2倍の双方向データレート
- NVMe、GPUやその他のアクセラレータを直接接続 可能な128レーンのPCle® Gen4インターフェース

4倍

競合製品に対する I/Oバンド幅² メモリー

- 競合製品に対して33%メモリーチャネル数が多い1
- CPU当たり最大4TBのDDR4メモリー容量
- 最高 3200MHz DDR4 Memoryまでのサポート

45% 競合に対するメモリバンド幅の向上3

Note:

- Each AMD EPYC processor has 8 memory channels. Each Intel Xeon Scalable processor has 6 memory channels. 8 6 = 2 + 6 = 0.33 AMD EPYC has 33% more memory channels. Class based on industry-standard pin-based (IGA) X86 process
 One EPYC 7002 Series has 433% for 14 times in more 10 bandwidth than one Intel Scalable processors RGM-21
- 3. AMD EPYC™ 7002 Series processors have 45% more memory bandwidth than Intel Scalable processors in the same class. ROM

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メモリースピードとバンド幅の性能向上

AMD EPYC™ 7002 シリーズ

DDR4 1DIMM per Channel Server*

DR RDIMM: 3200 MHz | LRDIMM: 3200 MHz

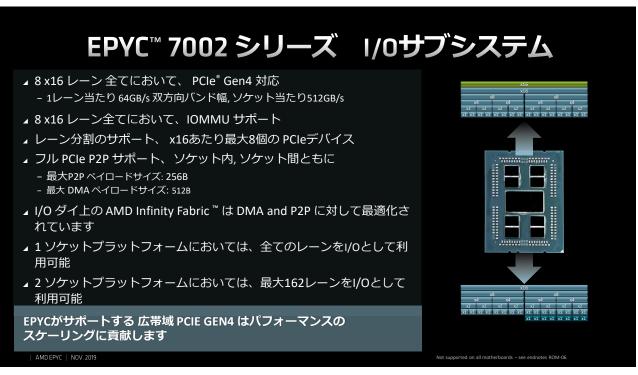


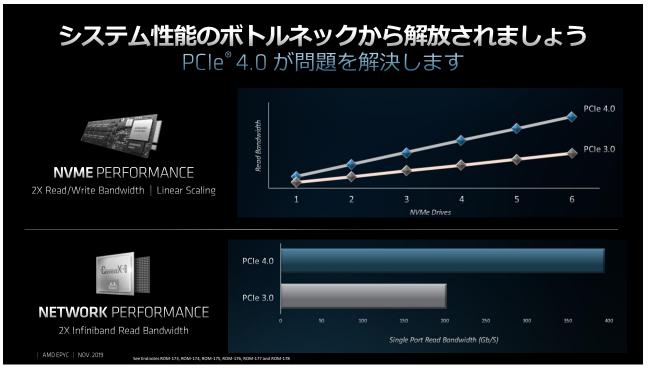
	Intel® Xeon® 2 nd Gen Scalable ("Cascade Lake SP")	AMD EPYC™ 7001 Series	AMD EPYC™ 7002 Series
2P サーバーシステムの最大理論 メモリバンド幅 (1DPC)	12 x DDR4-2933 = 282GB/s	16 x DDR4-2666 = 340GB/s	16 x DDR4-3200* = 410GB/s
AMD EPYC™ アドバンテージ		+21%	+45%

広帯域メモリーがパフォーマンスのスケーリングに貢献します

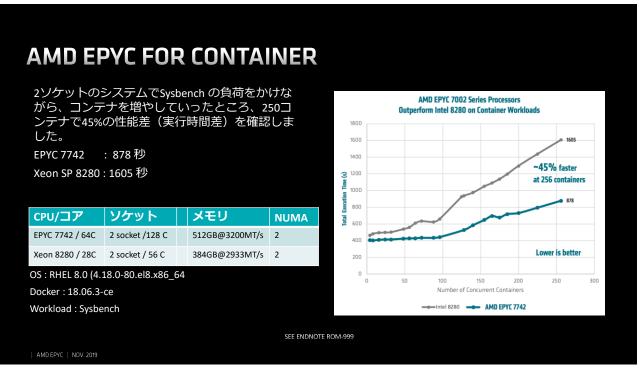
Not supported on all motherboards – see endnotes ROM-06 for detail

*AMD POR memory speeds in a one DIMM per channel system implementati

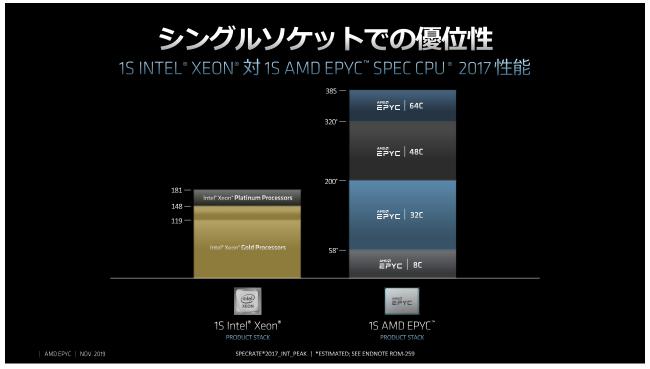


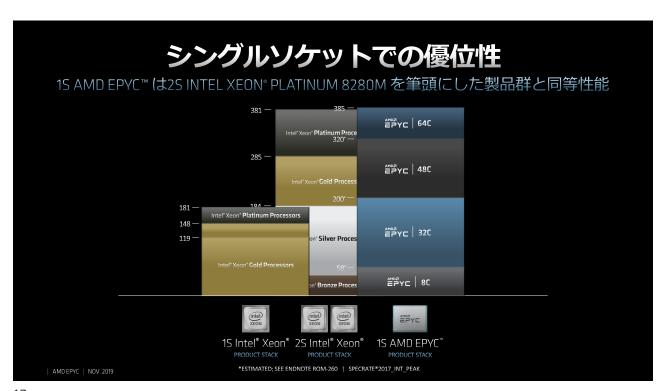
























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ENDNOTES

- ROM-06 Some supported features and functionality of 2nd Gen AMD EPYC™ processors require a BIOS update from your server manufacturer when used with a motherboard designed for the 1st Gen AMD EPYC series processor. A motherboard designed for 2nd Gen EPYC processors is required to enable all available functionality.
- ROM-07 Motherboards designed for 1st Gen EPYC processors may not be compatible with 2nd Gen AMD EPYC processors with a TDP greater than 200 watts. Contact the server manufacturer to confirm compatibility.
- ROM-09 AMD EPYC 7742 has 64 cores vs. Intel Platinum 8280 with 28 cores. 64 / 28 = 2.287 1.0 = 1.3 times (or 130% more). EPYC 7742 has 1.3x more cores.
- ROM-11 EPYC[®] 7002 series has 8 memory channels, supporting 3200 MHz DIMMs yielding 204.8 GB/s of bandwidth vs. the same class of Intel Scalable Gen 2 processors with
 only 6 memory channels and supporting 2933 MHz DIMMs yielding 140.8 GB/s of bandwidth. 204.8 / 140.8 = 1.454545 1.0 = .45 or .45% more. AMD EPYC has .45% more
 bandwidth. Class based on industry-standard pin-based (LGA) X86 processors.
- ROM-21 Based on processor lanes multiplied by PCle® bandwidth. PCle 4 = 16 GB/s link bandwidth vs. PCle 3 = 8 GB/s.
- ROM-38Results as of 8/7/2019 using SPECrate(R)2017_int_base. EPYC 7742 score of 682, https://spec.org/cpu2017/results/res2019q3/cpu2017-20190722-16242.html. Intel Platinum 8280L score 364, http://spec.org/cpu2017/results/res2019q2/cpu2017-20190429-12779.pdf, July 28, 2019. SPEC®, SPECrate® and SPEC CPU® are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information.
- ROM-42 Based on AMD internal testing of ANSYS FLUENT 19.1, Im6000_16m benchmark, as of July 17, 2019 of a 2P EPYC 7742 powered reference server versus a 2P Intel Xeon Platinum 8280 powered server. Results may vary.
- ROM-49 Based on AMD internal testing of LSTC LS-DYNA R9.3.0, neon benchmark, as of July 17, 2019 of a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-56 Based on AMD internal testing of Altair RADIOSS 2018, T10M benchmark, as of July 17, 2019 using a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 nowered server. Results may vary.
- ROM-63 Based on AMD internal testing of ESI VPS 2018.0, NEON4m benchmark, as of July 17, 2019 using a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-70 Based on AMD internal testing of Siemens PLM STAR-CCM+ 14.02.009, kcs_with_physics benchmark, as of July 17, 2019 using a 2P EPYC 7742 powered reference server versus a 2P Xeon Platinum 8280 powered server. Results may vary.
- ROM-113 AMD Internal testing as of 30July2019 of a 2P AMD EPYC 7742 powered reference platform versus a 2P Intel Platinum 8280 powered production server, on GROMACS version 2019.3 benchmark. Results may vary.

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- ROM-114 Based on SPECrate® 2017 peak integer scores. A 2P EPYC™ 7742 processor powered server has higher SPECrate® 2017_int_peak score of 749 and a base score of 682 as of August 7, 2019, http://spec.org/cpu2017/results/res2019q3/cpu2017-20190722-16242.html. The next hightest int_peak score with a 2P Intel Platinum 9282 of 676 and a base score of 643, http://spec.org/cpu2017/results/res2019q3/cpu2017-20190624-15369.pdf, on July 28, 2019. SPEC®, SPECrate® and SPEC CPU® are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information. ROM-07 Motherboards designed for 1st Gen EPYC processors may not be compatible with 2nd Gen AMD EPYC processors with a TDP greater than 200 watts. Contact the server manufacturer to confirm compatibility.
- ROM-173 AMD internal testing completed on 29Jul2019 on AMD reference platform configured with Samsung PCle Gen4 PM1733 NVMe 3.84TB drives compared to an Intel
 server from a major OEM configured PCle Gen3 Samsung PM1725b 1.6TB drives.
- ROM-174 AMD internal testing completed on 29Jul2019 on AMD reference platform configured with Samsung PCIe Gen4 PM1733 NVMe 3.84TB drives compared to an Intel server from a major OEM configured PCIe Gen3 Samsung PM1725b 1.6TB drives.
- ROM-175 AMD internal testing completed on 29Jul2019 on AMD reference platform configured with Samsung PCIe Gen4 PM1733 NVMe 3.84TB drives compared to an Intel server from a major OEM configured PCIe Gen3 Samsung PM1725b 1.6TB drives.
- ROM-176 AMD internal testing completed on 29Jul2019 on AMD reference platform configured with Samsung PCIe Gen4 PM1733 NVMe 3.84TB drives compared to an Intel server from a major OEM configured PCIe Gen3 Samsung PM1725b 1.6TB drives.
- ROM-177 AMD internal testing completed on 06Aug2019 on AMD reference platform configured with 2 x EPYC 7742 and a Mellanox ConnectX-6 InfiniBand using Windows 2019 compared to an Intel server from a major OEM configured with 2 x Intel Platinum 8280 processors and a Mellanox ConnectX-6 using Windows 2019.
- ROM-178 AMD internal testing completed on 06Aug2019 on AMD reference platform configured with 2 x EPYC 7742 and a Mellanox ConnectX-6 InfiniBand using Windows 2019 compared to an Intel server from a major OEM configured with 2 x Intel Platinum 8280 processors and a Mellanox ConnnectX-6 using Windows 2019.
- ROM-258 Slide represents both published and estimated SPECrate*2017_int_peak performance. Estimates as of July 3, 2019 for AMD EPYC 48C, 32C and 8C processors using computer modeling of preproduction parts and SPECrate*2017_int_peak internal testing results. Results may vary with production silicon testing. Published results for EPYC 64C processor as of August 7, 2019 https://spec.org/cpu2017/results/ress2019q3/cpu2017-20190722-16424. html. Intel results as of June 2019. Seon Platinum: http://spec.org/cpu2017/results/res2019q2/cpu2017-20190429-12779.pdf Xeon Gold: http://spec.org/cpu2017/results/res2019q2/cpu2017-20190404-11744.pdf Xeon Silver: http://spec.org/cpu2017/results/res2019q2/cpu2017-20190430-13444.pdf; Xeon Bronze: http://spec.org/cpu2017/results/res2019q3/cpu2017-20190624-15468.pdf. SPEC*, SPECrate* and SPEC CPU* are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information. ROM-258

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- ROM-259 Slide represents both published and estimated 1P SPECrate*2017_int_peak performance. Estimates as of July 3, 2019 for AMD EPYC 48C, 32C and 8C processors using computer modeling of preproduction parts and 1P SPECrate*2017_int_peak internal testing results. Results may vary with production silicon testing. Published results for 1P EPYC 64C processor as of August 7, 2019: http://spec.org/cpu2017/results/res2019q2/cpu2017/results/res2019q2/cpu2017-20190318-11230.pdf section of July 2019. Seon Fold: http://spec.org/cpu2017/results/res2019q2/cpu2017-20190611-15301.pdf and http://spec.org/cpu2017/results/res2019q2/cpu2017-20190611-15308.pdf. SPEC*, SPECrate* and SPEC CPU* are registered trademarks of the Standard Performance Evaluation Corporation. See www.spec.org for more information. ROM-259
- ROM-260 Slide represents both published and estimated IP and 2P SPECrate*2017_it.peak performance. Estimates as of July 3, 2019 for AMD EPYC 48C, 32C and 8C processors using computer modeling of preproduction parts and IP SPECrate*2017_int_peak internal testing results. Results may vary with production silicon testing. Published results for IP EPYC 64C processor as of August 7, 2019. https://spec.org/up2017/results/res2019q3/pu2017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-2019017-

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